

Final Product/Process Change Notification

Document #: FPCN22251Y Issue Date: 19 April 2018

Title of Change:	Long boot issue on the Ezairo 5920 hybrid for 0W	/635-004-XTP.
Proposed first ship date:	26 July 2018	
Contact information:	Contact your local ON Semiconductor Sales Offic	e or < <u>christophe.waelchli@onsemi.com</u> >
Samples:	Contact your local ON Semiconductor Sales Offic	e or < <u>christophe.waelchli@onsemi.com</u> >
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <pre>paul.syndergaard@onsemi.com</pre>	
Type of notification:	prior to implementation of the change.	on (FPCN) sentto customers. FPCNs are issued 90 days epted, unless an inquiry is made in writing within 30 <pcn. support@onsemi.com="">.</pcn.>
Change Part Identification:	A new OPN will be available and the chip ID will Old OPN: 0W635-004-XTP / Old chip ID: 1.02.00. New OPN: 0W635-006-XTP / New chip ID: 1.02.1	
Change category:	Wafer Fab Change Assembly Change	Test Change Other: Silicon Change
Change Sub-Category(s): Manufacturing Site Change/Addition Manufacturing Process Change		Datasheet/Product Doc change Shipping/Packaging/Marking Other:
Sites Affected:	ON Semiconductor Sites: ON Burlington, Canada	External Foundry/Subcon Sites: None

Description and Purpose:

On the current version of the Ezairo 5920 hybrid (OPN: 0W635-004-XTP), on a small percentage of parts, the VDDC voltage of the Ezairo 5900 DSP (used in the Ezairo 5920 hybrid) is not reaching its final value quick enough when VBAT is higher than 1.5V, which leads to a boot delay. A metal mask update of the Ezairo 5900 DSP was made to ensure the settling time of the VDDC voltage is better controlled. This will allow the Ezairo 5920 to always boot with the expected timing.

The OW635-004-XTP is being replaced by the OW635-006-XTP, which includes the Ezairo 5900 with the metal mask update mentioned above.

On the Ezairo 5900 DSP series, the chip version is commonly written as X.YY.ZZ, where X is the chip version number, YY is the major revision number, and ZZ is the minor revision number. Please refer to Section 2.9 DEVICE IDENTIFICATION of the HW reference manual of the Ezairo 5900 for more details.

The chip version of the Ezairo 5900 DSP used in 0W635-004-XTP (old version of Ezairo 5920) is 1.02.00. The chip version of the Ezairo 5900 DSP used in 0W635-006-XTP (new version of Ezairo 5920) is 1.02.10.

The datasheet for the 0W635-006-XTP is available on MyON.

The 0W635-006-XTP qualification data is available upon request.

	Before Change Description	After Change Description
Ezairo 5900	Metal2 reticle 380C: On a small percentage of parts, the VDDC voltage of the Ezairo 5900 DSP (used in the Ezairo 5920 hybrid) is not reaching its final value quickenough when VBAT is higher than 1.5V, which leads to a boot delay. Chip version is 1.02.00	Metal2 reticle 380C: A modification to the silicon has been made to ensure the settling time of VDDC voltage is better controlled so that the chip will always boot with the expected timing. Chip version is 1.02.10

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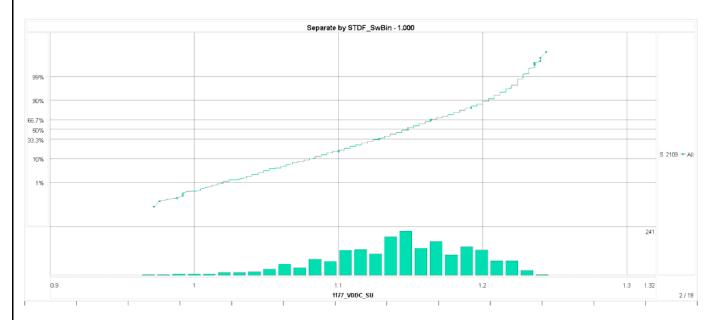
Issue Date: 19 April 2018

Reliability Data Summary:

See Ezairo 5900 FPCN22074Y called "Metal 2 update to reduce the regulator start-up time to avoid sporadic occurrence of long application startup when using VBAT > 1.5V."

Electrical Characteristic Summary:

The following graph shows the VDDC startup voltage after 100 ms on the 0W635-006-XTP. After 100 ms, VDDC reaches its controlled final value on all tested units.



List of Affected Standard Parts:

Current Part Number	New Part Number	Qualification Vehicle
0W635-004-XTP	0W635-006-XTP	0W635-004-XTP

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Appendix A:	Changed Products		
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